

New PCT National Phase Application
Docket No. 2691-000051/US

IN THE ABSTRACT

Please replace the Abstract with the attached revised
Abstract located at the end of this document.

ABSTRACT OF THE DISCLOSURE

A semiconductor polishing composition is disclosed. The composition includes fumed silica, the semiconductor polishing composition being an aqueous dispersion solution of fumed silica. A content of the fumed silica includes a particle diameter of 100 nm or less is 15% by volume or more based on a total amount of the fumed silica.